

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	14873	(chip or die) and semiconductor and bonding and wire and substrate	USPAT	OR	OFF	2005/12/07 10:00
L2	6458	(chip or die) and semiconductor and bonding and wire and substrate and resin	USPAT	OR	OFF	2005/12/07 10:01
L3	5710	(chip or die) and semiconductor and bonding and wire and substrate and resin and first and second	USPAT	OR	OFF	2005/12/07 10:02
L4	236	(first adj (chip or die)) and (second adj (chip or die)) and semiconductor and bonding and wire and substrate and resin	USPAT	OR	OFF	2005/12/07 10:05
L5	262	(first adj (chip or die)) and (second adj (chip or die)) and semiconductor and bonding and wire and substrate and resin	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/07 10:05